

SOT1444-8

wafer level chip-scale package; 49 bumps; 3.13 x 3.63 x 0.5 mm

11 August 2016

Package information

1. Package summary

Dimensions (mm)	3.13 x 3.63 x 0.5
Terminal position code	B (bottom)
Package type descriptive code	WLCSP49
Package outline version code	SOT1444-8
Manufacturer package code	SOT1444
Package type industry code	WLCSP
Package outline version description	wafer level chip-scale package; 49 bumps; 3.13 x 3.63 x 0.5 mm
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	X
Mounting method type	S (surface mount)
Package life cycle status	REL
Security status	COMPANY PUBLIC
Issue date	9-8-2016
Customer specific indicator	N
Maturity	Product

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A ₂	package height	0.275	-	0.3	0.325	mm
A	seated height	0.46	-	0.5	0.54	mm
D	package length	3.6	-	3.63	3.66	mm
E	package width	3.1	-	3.13	3.16	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	49	-	



2. Package outline

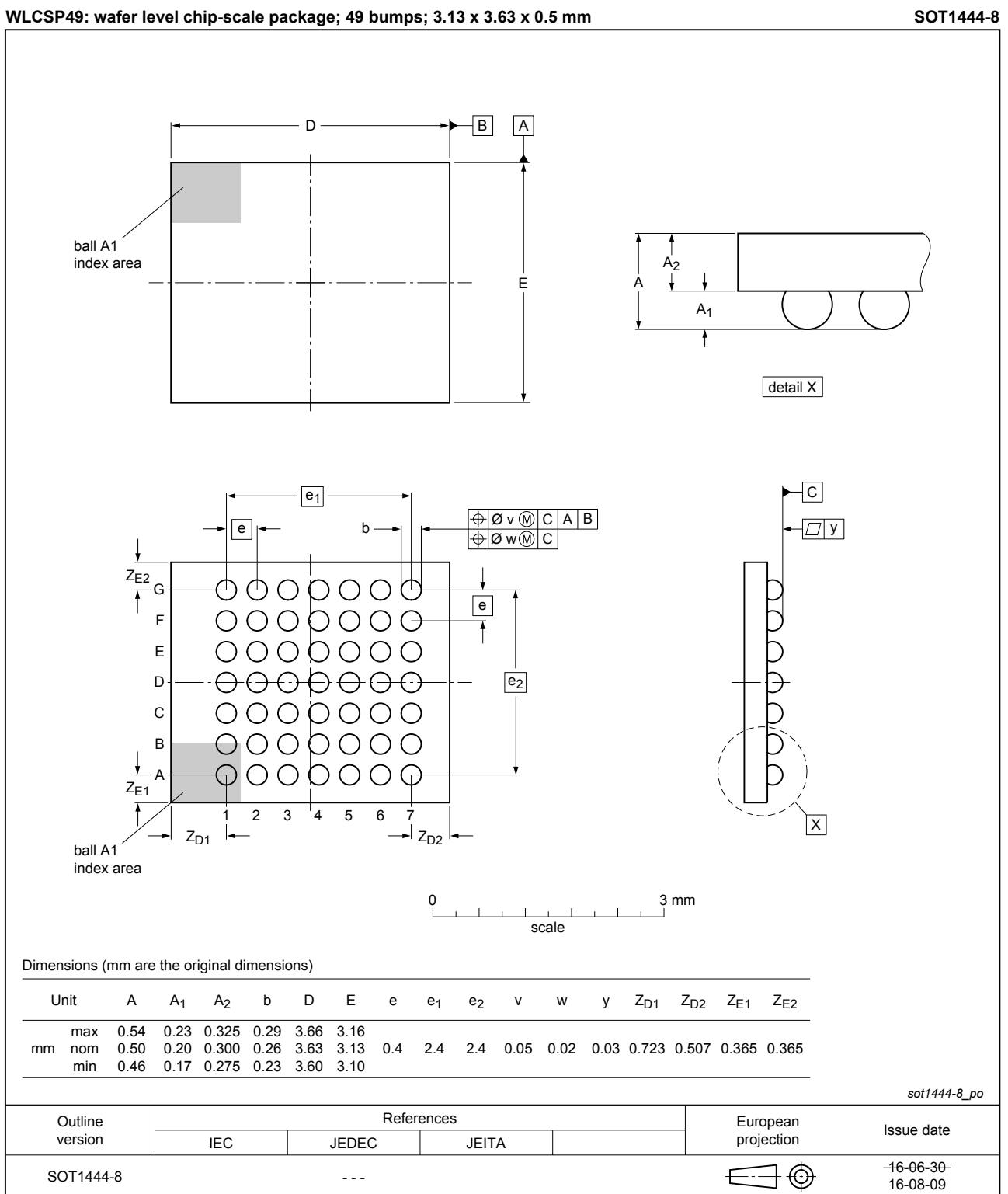


Fig. 1. Package outline WL CSP (SOT1444-8)

3. Legal information

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